

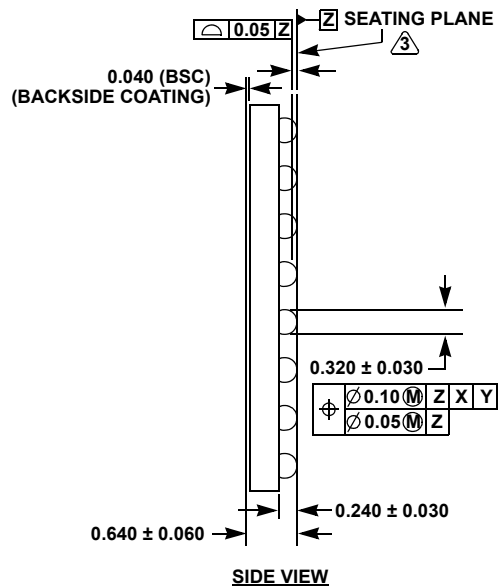
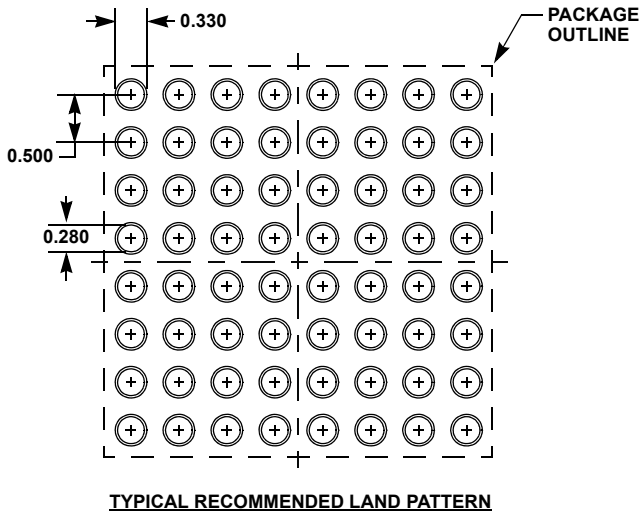
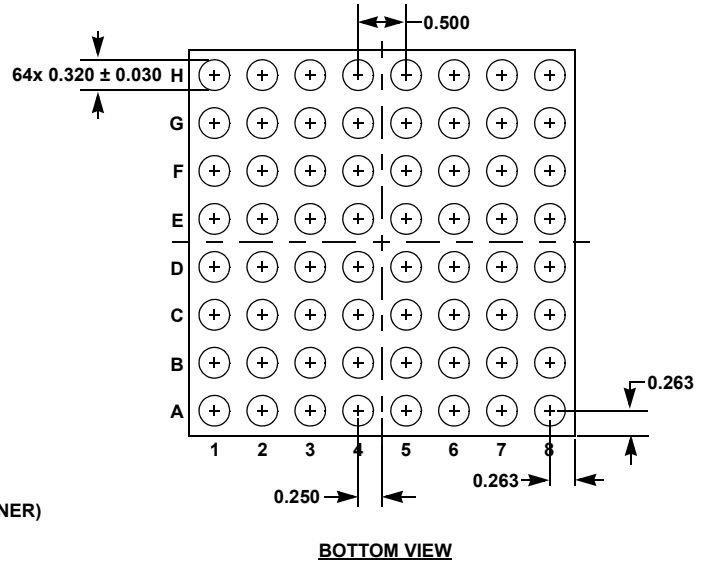
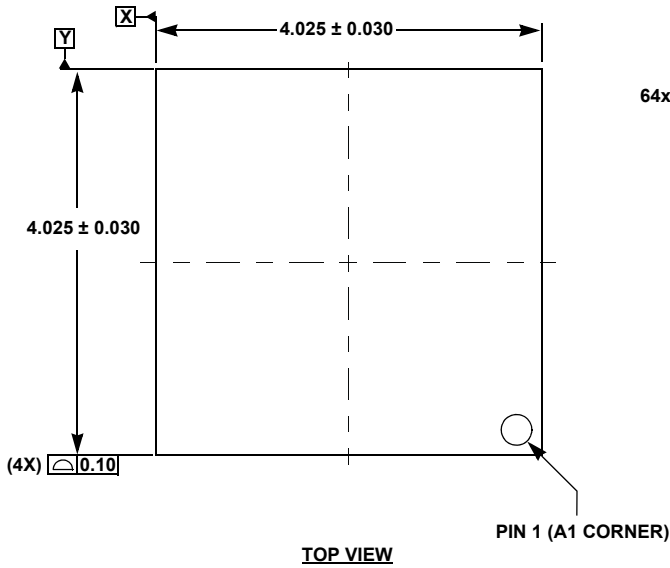
Plastic Packages for Integrated Circuits

Package Outline Drawing

W8x8.64A

8x8 Array 64 Balls Wafer Level Chip Scale Package (WLCSP) 0.5mm Pitch (BSC)

Rev 0, 7/14



NOTES:

1. All dimensions are in millimeters.
2. Dimension and tolerance conform to ASMEY14.5-1994.

③ NSMD refers to non-solder mask defined pad design per Intersil Technical Brief <http://www.intersil.com/data/tb/tb451.pdf>